

Hex D flip-flops

54F174

FEATURES

- Six edge-triggered D-type flip-flops
- Buffered common Clock
- Buffered, asynchronous Master Reset

ORDERING INFORMATION

DESCRIPTION	ORDER CODE	PACKAGE DESIGNATOR*
16-Pin Ceramic DIP	54F174/BEA	GDIP1-T16
16-Pin Ceramic Flat Pack	54F174/BFA	GDFP2-F16
20-Pin Ceramic LLCC	54F174/B2A	CQCC2-N20

* MIL-STD 1835 or Appendix A of 1995 Military Data Handbook

DESCRIPTION

The 54F174 has six edge-triggered flip-flops with individual D inputs and Q outputs. The common buffered Clock (CP) and Master Reset (MR) inputs load and reset (clear) all flip-flops simultaneously.

The register is fully edge-triggered. The state of each D input, one set-up time before the Low-to-High clock transition is transferred to the corresponding flip-flop's Q output.

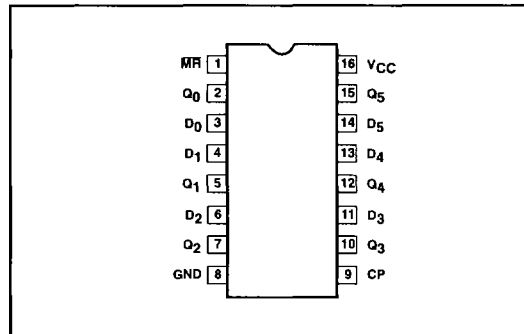
All outputs will be forced LOW independent of Clock or Data inputs by a Low voltage level on the MR input. The device is useful for applications where true outputs only are required, and the Clock and Master Reset are common to all storage elements.

INPUT AND OUTPUT LOADING AND FAN-OUT TABLE

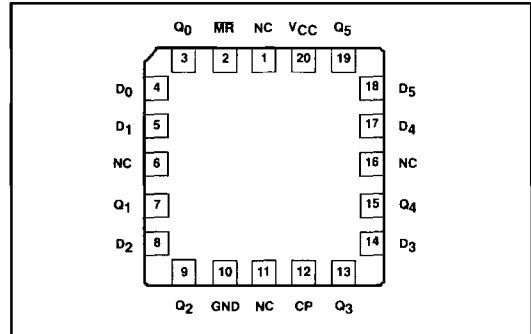
PINS	DESCRIPTION	54F (U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
D ₀ - D ₅	Data inputs	1.0/1.0	20µA/0.6mA
CP	Clock pulse inputs (active rising edge)	1.0/1.0	20µA/0.6mA
MR	Master Reset input (active Low)	1.0/5	20µA/0.6mA
Q ₀ - Q ₅	Data outputs	50/33	1.0mA/20mA

NOTE: One (1.0) FAST Unit Load (U.L.) is defined as: 20µA in the High state and 0.6mA in the Low state.

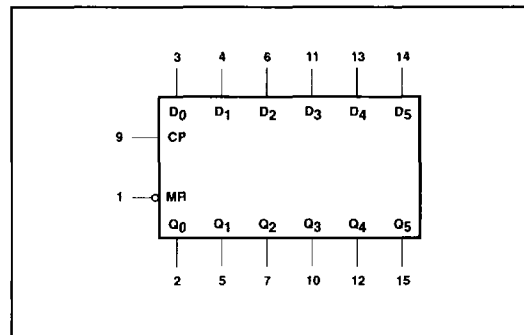
PIN CONFIGURATION



LLCC LEAD CONFIGURATION



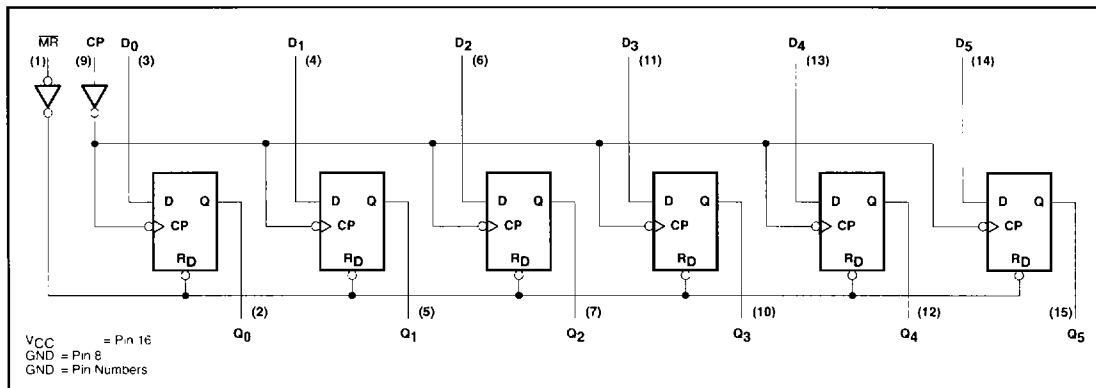
LOGIC SYMBOL



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LOGIC DIAGRAM



FUNCTION TABLE

OPERATING MODE	INPUTS			OUTPUTS
	MR	CP	D _n	Q _n
Reset (clear)	L	X	X	L
Load "1"	H	↑	h	H
Load "0"	H	↑	l	L

- H = High voltage level steady state.
- h = High voltage level one setup time prior to the Low-to-High Clock transition.
- L = Low voltage level steady state.
- l = Low voltage level one setup time prior to the Low-to-High Clock transition.
- X = Don't Care.
- ↑ = Low-to-High Clock transition.

ABSOLUTE MAXIMUM RATINGS

(Operation beyond the limits set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free-air temperature range.)

SYMBOL	PARAMETER	RATING	UNIT
V _{CC}	Supply voltage range	-0.5 to +7.0	V
V _I	Input voltage range	-0.5 to +7.0	V
I _I	Input current range	-30 to +5.0	mA
V _O	Voltage applied to output in High output state range	-0.5 to +V _{CC}	V
I _O	Current applied to output in Low output state	40	mA
T _{STG}	Storage temperature range	-65 to +150	°C

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	LIMITS			UNIT
		Min	Nom	Max	
V _{CC}	Supply voltage	4.5	5.0	5.5	V
V _{IH}	High-level input voltage	2.0			V
V _{IL}	Low-level input voltage			+0.8	V
I _{IK}	Input clamp current			-18	mA
I _{OH}	High-level output current			-1.0	mA
I _{OL}	Low-level output current			20	mA
T _A	Operating free-air temperature range	-55		+125	°C

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DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature range unless otherwise noted.)

SYMBOL	PARAMETER	TEST CONDITIONS ¹	LIMITS			UNIT
			Min	Typ ²	Max	
V _{OH}	High-level output voltage	V _{CC} = Min, V _{IH} = Min, I _{OH} = Max	2.5			V
V _{OL}	Low-level output voltage	V _{CC} = Min, V _{IL} = Max, I _{OL} = Max		0.35	0.50	V
V _{IK}	Input clamp voltage	V _{CC} = Min, I _I = I _{IK}		-0.73	-1.2	V
I _{IH2}	Input current at maximum input voltage	V _{CC} = Max, V _I = 7.0V			100	μA
I _{IH1}	High-level input current	V _{CC} = Max, V _I = 2.7V		1	20	μA
I _{IL}	Low-level input current	V _{CC} = Max, V _I = 0.5V		-0.4	-0.6	mA
I _{OS}	Short-circuit output current ³	V _{CC} = Max	-60	-80	-150	mA
I _{CC}	Supply current (total)	V _{CC} = Max, D _n = MR = 4.5V, CP = ↑		35	45	mA

AC ELECTRICAL CHARACTERISTICS

SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS					UNIT
			T _A = +25°C V _{CC} = +5.0V C _L = 50pF, R _L = 500Ω			T _A = -55°C to +125°C V _{CC} = +5.0V ± 10% C _L = 50pF, R _L = 500Ω		
			Min	Typ	Max	Min	Max	
f _{MAX}	Maximum Clock frequency	Waveform 1	80	100		80		MHz
t _{PLH} t _{PHL}	Propagation delay CP to Q _n	Waveform 1	3.5 4.5	5.5 6.0	8.0 10.0	3.0 4.0	9.5 11.5	ns ns
t _{PHL}	Propagation delay MR to Q _n	Waveform 3	5.0	8.5	14.0	4.5	15.5	ns

NOTES:

- For conditions shown as Min or Max, use the appropriate value specified under recommended operating conditions for the applicable type and function table operating mode.
- All typical values are at V_{CC} = 5V, T_A = 25°C.
- Not more than one output should be shorted at a time. For testing I_{OS}, the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a High output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

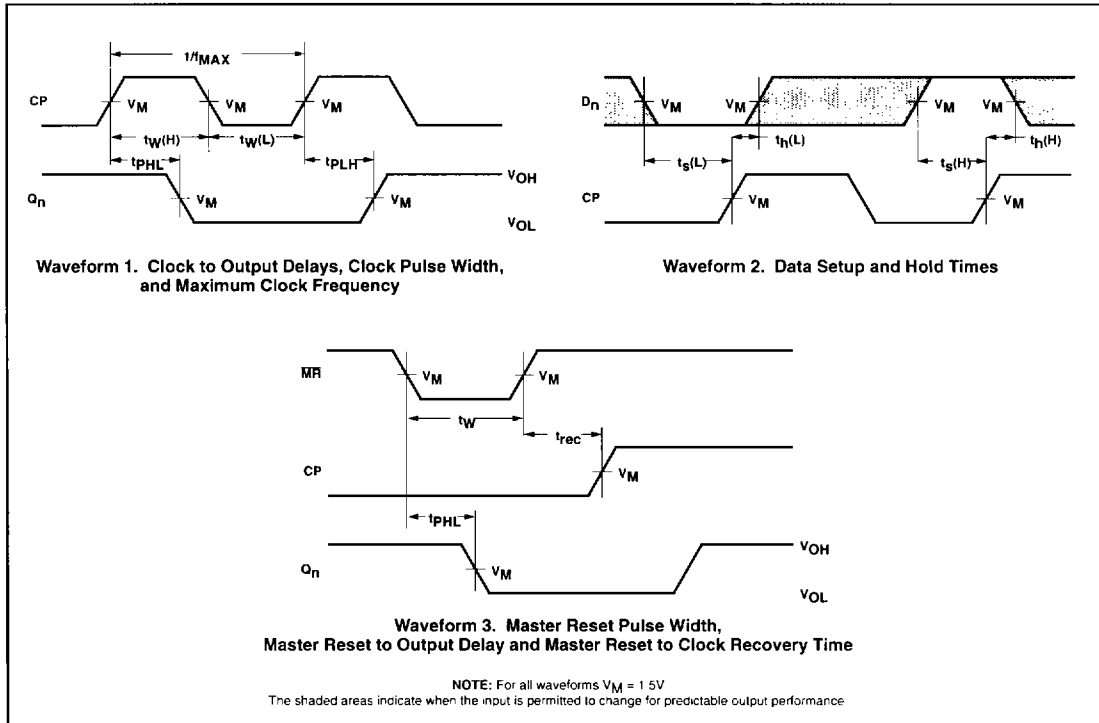
AC SETUP REQUIREMENTS

SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS					UNIT
			T _A = +25°C V _{CC} = +5.0V C _L = 50pF, R _L = 500Ω			T _A = -55°C to +125°C V _{CC} = +5.0V ± 10% C _L = 50pF, R _L = 500Ω		
			Min	Typ	Max	Min	Max	
t _s (H) t _s (L)	Setup time, High or Low D _n to CP	Waveform 2	4.0 4.0			4.0 4.0		ns ns
t _h (H) t _h (L)	Hold time, High or Low D _n to CP	Waveform 2	0 0			0 0		ns ns
t _w (H) t _w (L)	CP pulse width, High or Low	Waveform 1	4.0 6.0			4.0 6.0		ns ns
t _w (L)	MR pulse width Low	Waveform 3	5.0			5.0		ns
t _{rec}	Recovery time MR to CP	Waveform 3	5.0			6.0		ns

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AC WAVEFORMS



TEST CIRCUIT AND WAVEFORM

